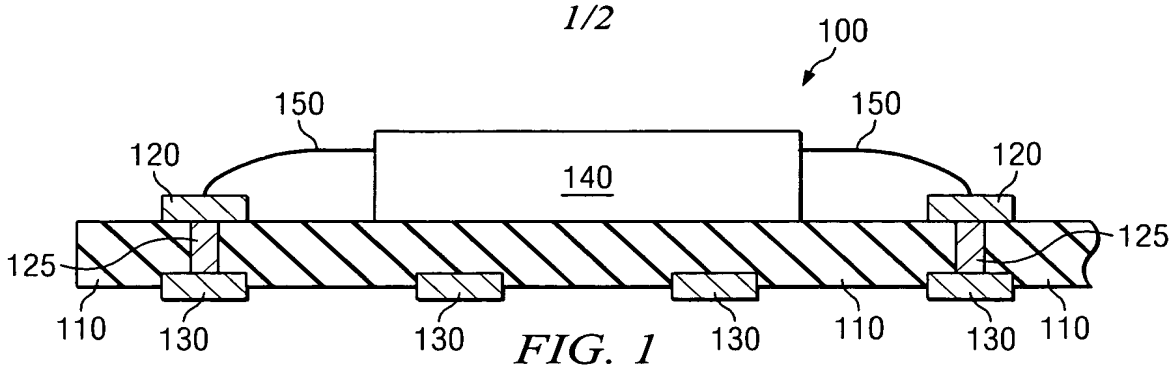


FIG. 1

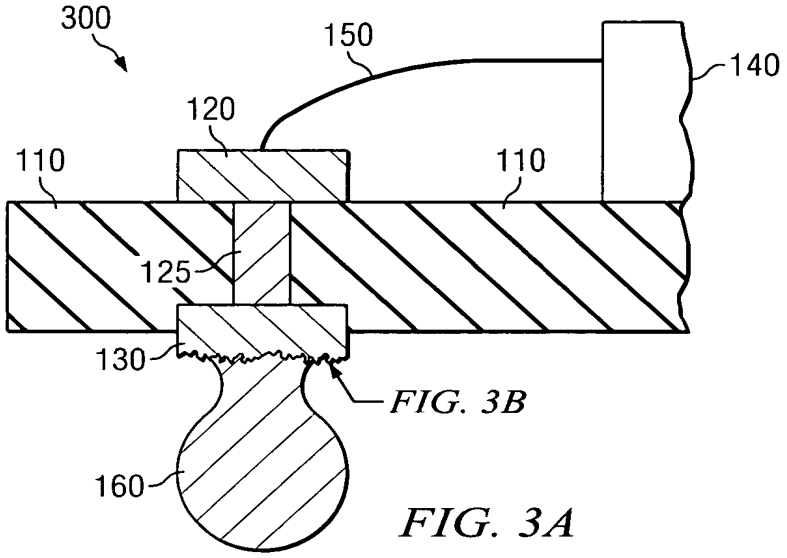


FIG. 3A

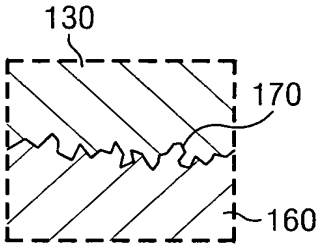


FIG. 3B

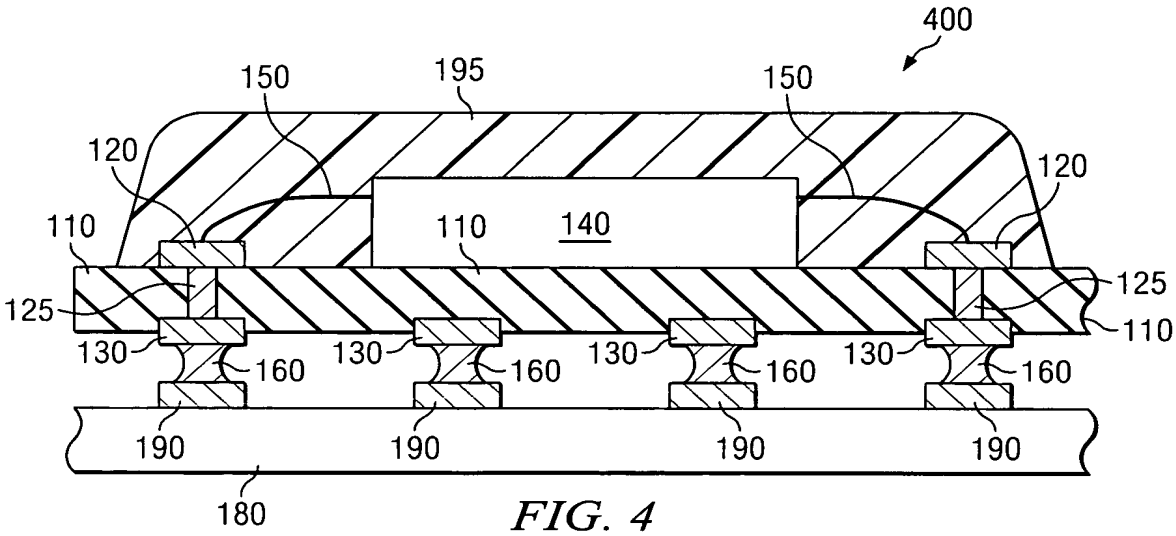
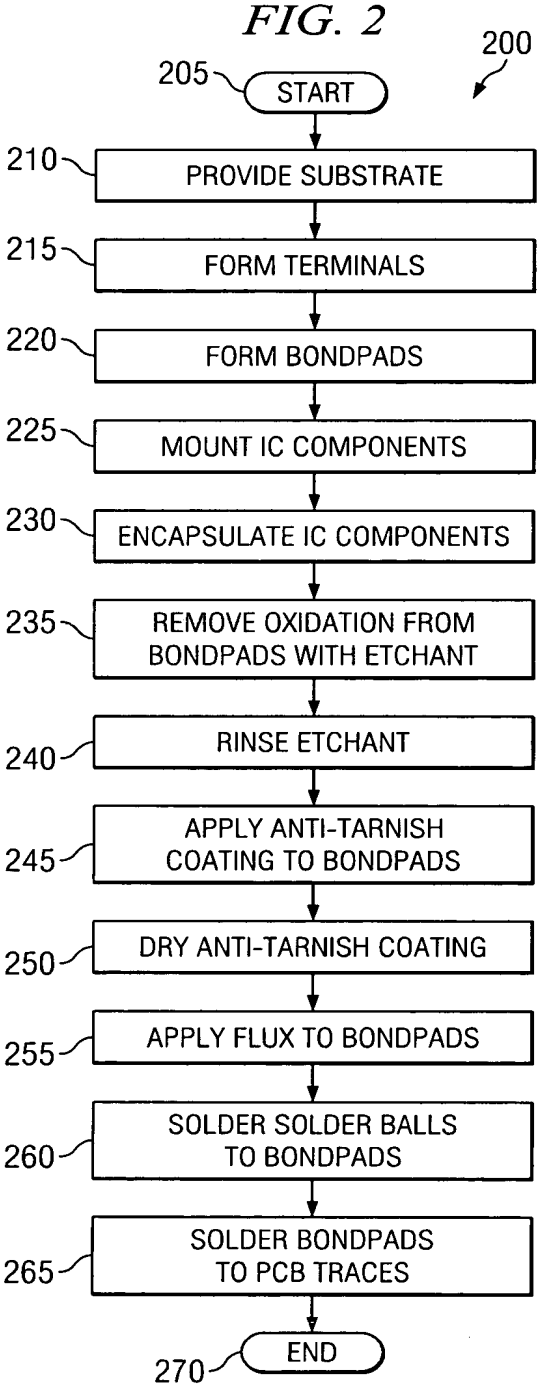


FIG. 4

FIG. 2


200
205
START
210
PROVIDE SUBSTRATE
215
FORM TERMINALS
220
FORM BONDPADS
225
MOUNT IC COMPONENTS
230
ENCAPSULATE IC COMPONENTS
235
REMOVE OXIDATION FROM BONDPADS WITH ETCHANT
240
RINSE ETCHANT
245
APPLY ANTI-TARNISH COATING TO BONDPADS
250
DRY ANTI-TARNISH COATING
255
APPLY FLUX TO BONDPADS
260
SOLDER SOLDER BALLS TO BONDPADS
265
SOLDER BONDPADS TO PCB TRACES
270
END